

OSY5XNEHE1E

VER C.1

Features

- Highest luminous flux
- Super energy efficiency
- Long Lifetime Operation
- Superior UV Resistance

■Applications

- Read lights (car, bus, aircraft)
- Portable (flashlight, bicycle)
- Bollards / Security / Garden
- Traffic signaling / Beacons
- In door / Out door Commercial lights
- Automotive Ext

■Absolute Maximum Rating

Item	Symbol	Value	Unit
DC Forward Current	$\mathbf{I}_{\mathbf{F}}$	200	mA
Pulse Forward Current*	I _{FP}	250	mA
Reverse Voltage	VR	5	V
Power Dissipation	PD	600	mW
Operating Temperature	Topr	-30 ~ +85	°C
Storage Temperature	Tstg	-40~ +100	°C
Lead Soldering Temperature	Tsol	260°C /5sec	-

Directivity

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14.5

Cathode(-)

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Anode -

Unit:mm

Tolerance:±0.30mm

- Cathode

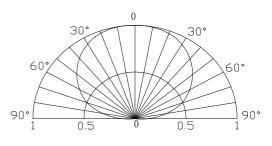
•Outline Dimension

Anode(+)

-5.06-

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(Ta=25°C)



*Pulse width Max.10ms Duty ratio max 1/10

■Electrical -Optical Characteristics (Ta=25°C)

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
DC Forward Voltage	\mathbf{V}_{F}	IF=150mA	2.0	2.5	3.0	V
DC Reverse Current	IR	V _R =5V	-	-	10	μΑ
Domi. Wavelength	λ_D	I _F =150mA	585	590	595	nm
Luminous Flux	Φv	I _F =150mA	15	20	-	lm
50% Power Angle	2 0 1/2	I _F =150mA	-	140	-	deg

*1 Tolerance of measurements of dominant wavelength is ± 1 nm

*2 Tolerance of measurements of luminous Flux is $\pm 15\%$

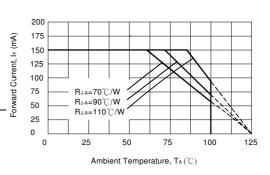
*3 Tolerance of measurements of forward voltage is ± 0.1 V

Note: Don't drive at rated current more than 5s without heat sink for Xeon H emitter series.

LED & Application Technologies



■Forward Operating Current (DC)









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■ Soldering Heat Reliability :

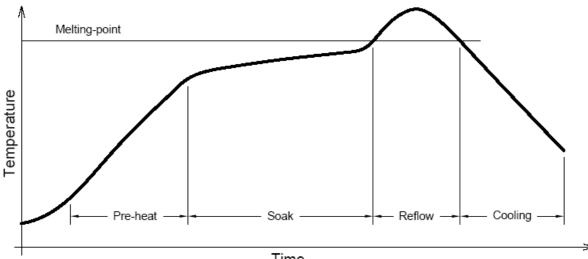
Reflow soldering Profile

- Reflow soldering should not be done more than two times.
- \cdot When soldering, do not put stress on the LEDs during heating.
- · After soldering, do not warp the circuit board.
- · Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,

a double-head soldering iron should be used. It should be confirmed beforehand whether the

characteristics of the LEDs will or will not be damaged by repairing.

Solder			
Average ramp-up rate = 3°C/sec. max.			
Preheat temperature: 150°~180°C			
Preheat time = 120 sec. max.			
Ramp-down rate = 6° C/sec. max.			
Peak temperature = 220° C max.			
Time within 3°C of actual			
peak temperature = 25 sec. max.			
Duration above 200°C is 40 sec. max.			



Time

